

**Amendments to the Claims:**

This Listing of Claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1-7. (Previously Cancelled)

8. (Currently Amended) A method for manufacturing a glass substrate of an information recording medium by polishing a surface of a glass workpiece with a polishing pad,

wherein the polishing pad comprises a nap layer having an inner layer and an outer layer, wherein the inner layer comprises a plurality of closed cells, and a plurality of pores are formed on the surface of the outer layer, and wherein the sizes of said pores are minute compared to those of said closed cells, said pores having an opening size of from 10 to 60  $\mu$ m,

wherein polishing includes a first polishing step for subjecting a surface of the glass workpiece to rough polishing, and a second polishing step for subjecting the surface of the glass workpiece to precision polishing so that the surface is further smoothed,

wherein the polishing pad is used in a second polishing step.

9. (Previously Presented) The method according to claim 8, wherein said polishing pad comprises from 400 to 10,000 of said pores in 1  $\text{mm}^2$ .

10. (Previously Presented) The method according to claim 8, wherein a compression deformation amount of said polishing pad is 40 to 60  $\mu\text{m}$ , wherein the compression deformation amount is computed by subtracting the thickness of the polishing pad when compressed to the limit along the thickness from the original thickness.

11. (Cancelled Herein)

12. (Currently Amended) The method according to claim 8, wherein the glass workpiece is one of a plurality of glass workpieces that are simultaneously polished on the same apparatus ~~by the method according to claim 8~~, wherein the variation of the thickness of removal layers among the glass workpieces is equal to or less than 0.2  $\mu\text{m}$ .

13-14. (Previously Cancelled)

15. (New) A method for manufacturing a glass substrate of an information recording medium by polishing a surface of a glass workpiece with a polishing pad,

wherein the polishing pad comprises a nap layer having an inner layer and an outer layer, wherein the inner layer comprises a plurality of closed cells, and a plurality of pores are formed on the surface of the outer layer, and wherein the sizes of said pores are minute compared to those of said closed cells,

wherein polishing includes a first polishing step for subjecting a surface of the glass workpiece to rough polishing, and a second polishing step for subjecting the surface of the glass workpiece to precision polishing so that the surface is further smoothed,

wherein the polishing pad is used in a second polishing step,

wherein said polishing pad comprises from 400 to 10,000 of said pores in 1 mm<sup>2</sup>,

wherein a compression deformation amount of the polishing pad is 40 to 60 µm, wherein the compression deformation amount is computed by subtracting the thickness of the polishing pad when compressed to the limit along the thickness from the original thickness, and,

wherein said pores have an opening size of from 10 to 60 µm.

16. (New) A method for manufacturing a glass substrate of an information recording medium by polishing a surface of a glass workpiece with a polishing pad, wherein the polishing pad has a nap layer having an inner layer and an outer layer, wherein the inner layer comprises a plurality of closed cells, and a plurality of pores are formed on the surface of the outer layer, and wherein the sizes of said pores are minute compared to those of said closed cells,

wherein polishing includes a first polishing step for subjecting a surface of the glass workpiece to rough polishing, and a second polishing step for subjecting the surface of the glass workpiece to precision polishing so that the surface is further smoothed, wherein the polishing pad is used in the second polishing step,

wherein the second polishing step includes a former polishing and a latter polishing, in the former and the latter polishing, different sizes of polishing agents are used.

17. (New) The method according to Claim 16, further comprising a rinse process with a cleaning liquid performed between the former polishing and the latter polishing.

18. (New) The method according to Claim 16, wherein the polishing agent used in the latter polishing is smaller in size than the polishing agent used in the former polishing.